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(54) Title: STRESS-REDUCED NI-P/PD STACKS FOR BONDABLE WAFER SURFACES

(57) Abstract: The invention relates to a substrate having a bondable metal coating comprising, in this order, on an Alor Cu surface: (a) a Ni-P layer, (b) a Pd layer and, optionally, (c) an Au layer, wherein the thickness of the Ni-P layer (a) is 0.2 to 10 m, the thickness of the Pd layer (b) is 0.05 to 1.0 m and the thickness of the optional Au layer (c) is 0.01 to 0.5 m, and wherein the Ni-P layer (a) has a P content of 10.5 to 14 wt.-%. The deposit internal stress of the resulting Ni-P/Pd stack is not higher than 34.48M-Pa (5,000psi). Further, a process for the preparation of such a substrate is described.



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